

OptiMOS™ Small-Signal MOSFET, -60V
Features

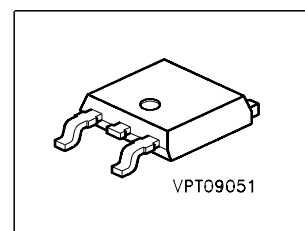
- ° P-channel
- ° Normal level
- ° AEC-Q101 Qualified
- ° 100% avalanche tested
- ° Pb-free lead plating; RoHS compliant
- ° Halogen-free according to IEC61249-2-21

Product Summary

Drain source voltage	V_{DS}	-60	V
Drain-source on-state resistance	$R_{DS(on)}$	0.13	Ω
Continuous drain current	I_D	-18.6	A

Product validation

- ° Qualified for automotive applications. Product validation according to AEC-Q101



Type	Package
SPD18P06P G	PG-TO252-3

Pin 1	PIN 2/4	PIN 3
G	D	S

Maximum Ratings, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current $T_C = 25\text{ °C}$ $T_C = 100\text{ °C}$	I_D	-18.6 -13.2	A
Pulsed drain current $T_C = 25\text{ °C}$	I_D puls	-74.4	
Avalanche energy, single pulse $I_D = -18.6\text{ A}$, $V_{DD} = -25\text{ V}$, $R_{GS} = 25\ \Omega$	E_{AS}	150	mJ
Avalanche energy, periodic limited by T_{jmax}	E_{AR}	8	
Reverse diode dv/dt $I_S = -18.6\text{ A}$, $V_{DS} = -48\text{ V}$, $di/dt = 200\text{ A}/\mu\text{s}$, $T_{jmax} = 175\text{ °C}$	dv/dt	6	kV/ μs
Gate source voltage	V_{GS}	± 20	V
Power dissipation $T_C = 25\text{ °C}$	P_{tot}	80	W
Operating and storage temperature	T_j , T_{stg}	-55...+175	$^{\circ}\text{C}$
IEC climatic category; DIN IEC 68-1		55/175/56	

Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Characteristics					
Thermal resistance, junction - case	R_{thJC}	-	-	1.85	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}	-	-	100	
SMD version, device on PCB: @ min. footprint @ 6 cm ² cooling area ¹⁾	R_{thJA}	-	-	75 50	

Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Static Characteristics					
Drain- source breakdown voltage $V_{GS} = 0\text{ V}$, $I_D = -250\text{ }\mu\text{A}$	$V_{(BR)DSS}$	-60	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = -1\text{ mA}$	$V_{GS(th)}$	-2.1	-3	-4	
Zero gate voltage drain current $V_{DS} = -60\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 25\text{ °C}$ $V_{DS} = -60\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 150\text{ °C}$	I_{DSS}	-	-0.1 -10	-1 -100	μA
Gate-source leakage current $V_{GS} = -20\text{ V}$, $V_{DS} = 0\text{ V}$	I_{GSS}	-	-10	-100	nA
Drain-source on-state resistance $V_{GS} = -10\text{ V}$, $I_D = -13.2\text{ A}$	$R_{DS(on)}$	-	0.1	0.13	Ω

¹Device on 40mm*40mm*1.5mm epoxy PCB FR4 with 6cm² (one layer, 70 μm thick) copper area for drain connection. PCB is vertical without blown air.

Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Transconductance $V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$, $I_D = -13.2\text{ A}$	g_{fs}	4	8	-	S
Input capacitance $V_{GS} = 0\text{ V}$, $V_{DS} = -25\text{ V}$, $f = 1\text{ MHz}$	C_{iss}	-	690	860	pF
Output capacitance $V_{GS} = 0\text{ V}$, $V_{DS} = -25\text{ V}$, $f = 1\text{ MHz}$	C_{oss}	-	230	290	
Reverse transfer capacitance $V_{GS} = 0\text{ V}$, $V_{DS} = -25\text{ V}$, $f = 1\text{ MHz}$	C_{rss}	-	95	120	
Turn-on delay time $V_{DD} = -30\text{ V}$, $V_{GS} = -10\text{ V}$, $I_D = -13.2\text{ A}$, $R_G = 2.7\text{ }\Omega$	$t_{d(on)}$	-	12	18	ns
Rise time $V_{DD} = -30\text{ V}$, $V_{GS} = -10\text{ V}$, $I_D = -13.2\text{ A}$, $R_G = 2.7\text{ }\Omega$	t_r	-	5.8	8.7	
Turn-off delay time $V_{DD} = -30\text{ V}$, $V_{GS} = -10\text{ V}$, $I_D = -13.2\text{ A}$, $R_G = 2.7\text{ }\Omega$	$t_{d(off)}$	-	24.5	37	
Fall time $V_{DD} = -30\text{ V}$, $V_{GS} = -10\text{ V}$, $I_D = -13.2\text{ A}$, $R_G = 2.7\text{ }\Omega$	t_f	-	11	16.5	

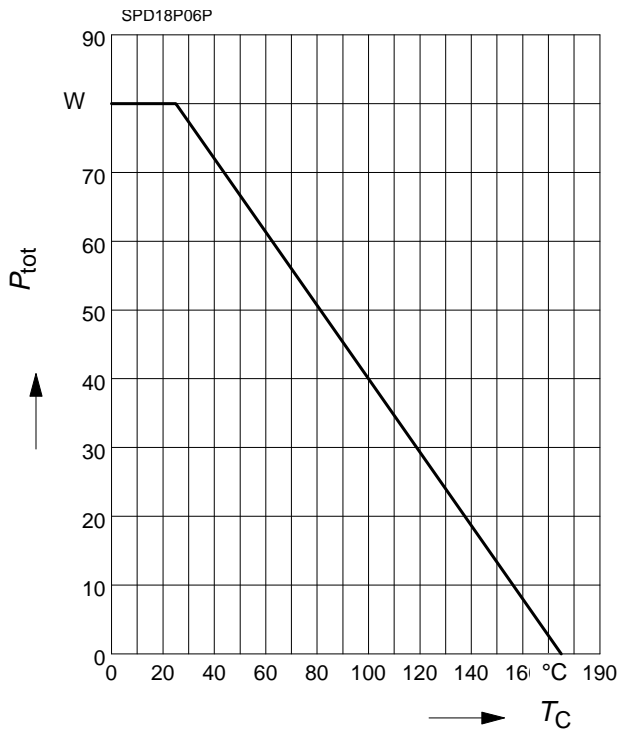
Electrical Characteristics, at $T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Dynamic Characteristics					
Gate to source charge $V_{DD} = -48\text{ V}, I_D = -18.6\text{ A}$	Q_{gs}	-	4.4	6.6	nC
Gate to drain charge $V_{DD} = -48\text{ V}, I_D = -18.6\text{ A}$	Q_{gd}	-	9.3	14	
Gate charge total $V_{DD} = -48\text{ V}, I_D = -18.6\text{ A}, V_{GS} = 0\text{ to }-10\text{ V}$	Q_g	-	22	33	
Gate plateau voltage $V_{DD} = -48\text{ V}, I_D = -18.6\text{ A}$	$V_{(plateau)}$	-	-5.56	-	V

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
Reverse Diode					
Inverse diode continuous forward current $T_C = 25\text{ °C}$	I_S	-	-	-18.6	A
Inverse diode direct current, pulsed $T_C = 25\text{ °C}$	I_{SM}	-	-	-74.4	
Inverse diode forward voltage $V_{GS} = 0\text{ V}, I_F = -18.6\text{ A}$	V_{SD}	-	-1	-1.33	V
Reverse recovery time $V_R = -30\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	t_{rr}	-	70	105	ns
Reverse recovery charge $V_R = -30\text{ V}, I_F = I_S, di_F/dt = 100\text{ A}/\mu\text{s}$	Q_{rr}	-	139	208	nC

Power dissipation

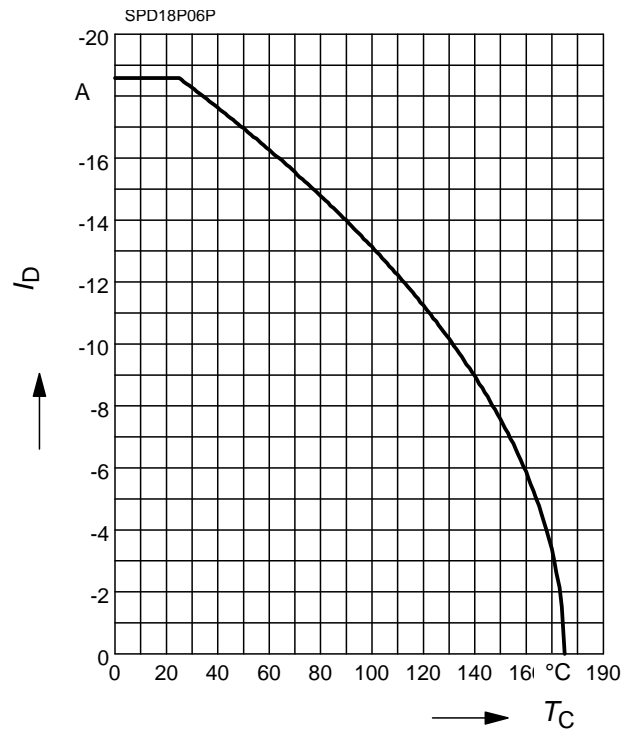
$$P_{tot} = f(T_C)$$



Drain current

$$I_D = f(T_C)$$

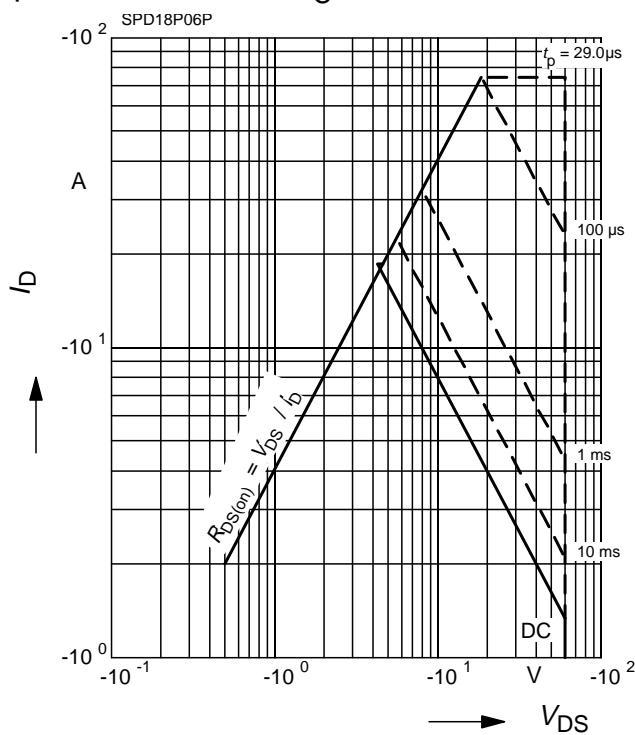
parameter: $V_{GS} \geq 10\text{ V}$



Safe operating area

$$I_D = f(V_{DS})$$

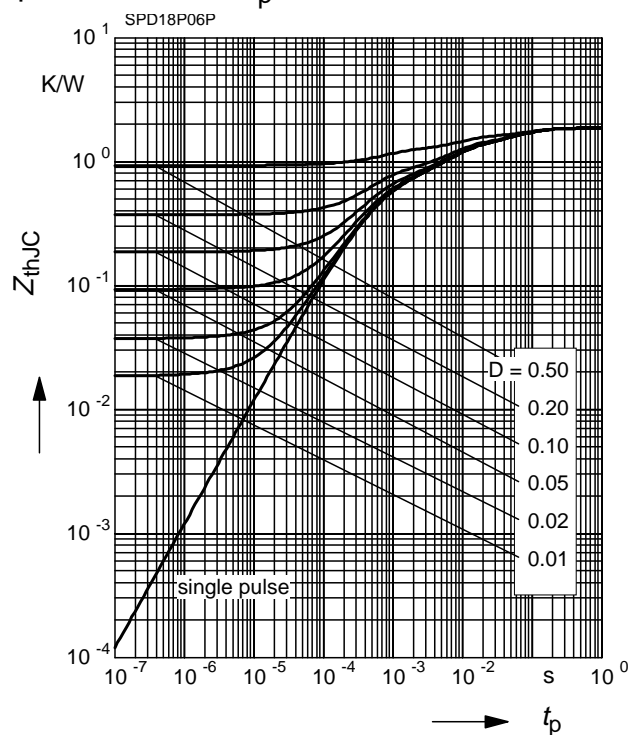
parameter: $D = 0$, $T_C = 25\text{ }^\circ\text{C}$



Transient thermal impedance

$$Z_{thJC} = f(t_p)$$

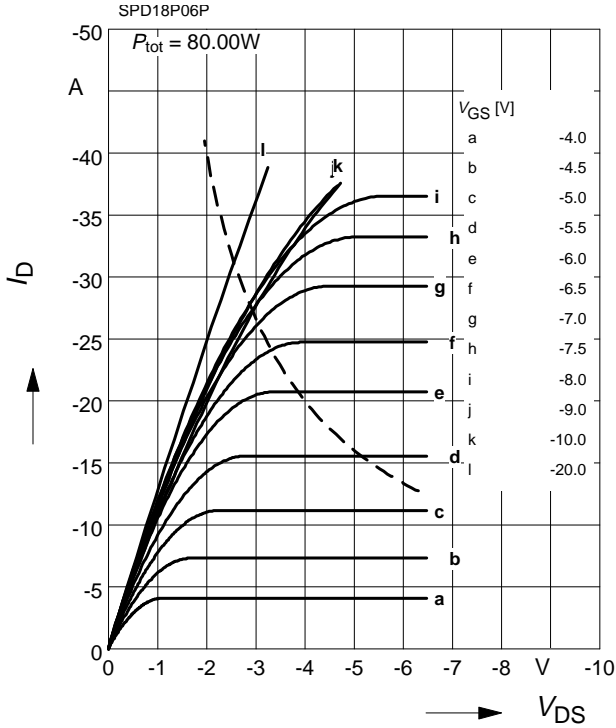
parameter: $D = t_p/T$



Typ. output characteristic

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

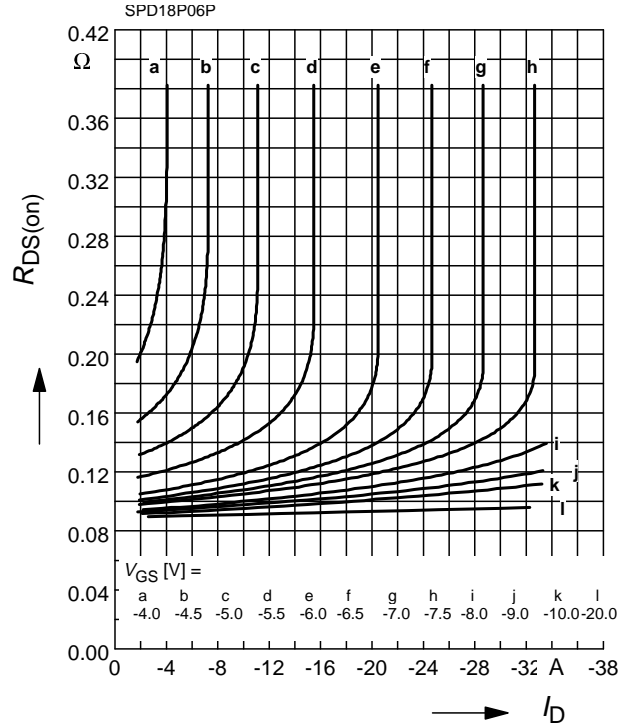
parameter: $t_p = 80 \mu\text{s}$



Typ. drain-source-on-resistance

$R_{DS(on)} = f(I_D)$

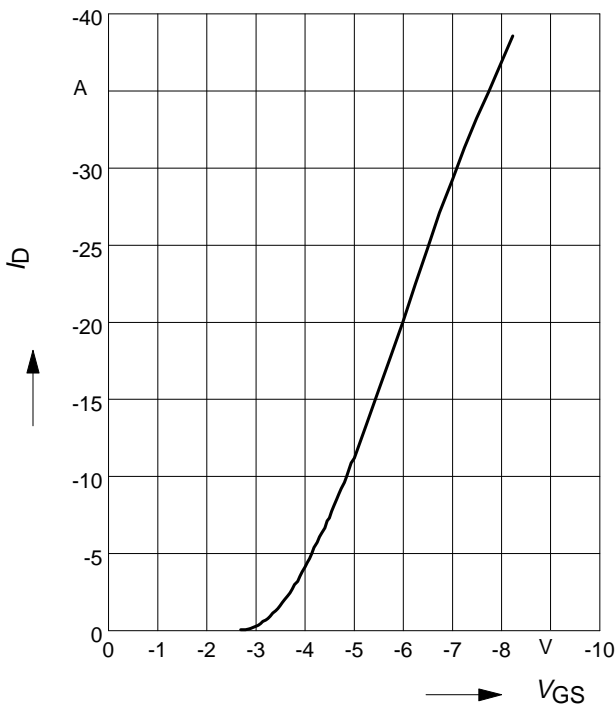
parameter: V_{GS}



Typ. transfer characteristics $I_D = f(V_{GS})$

$V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

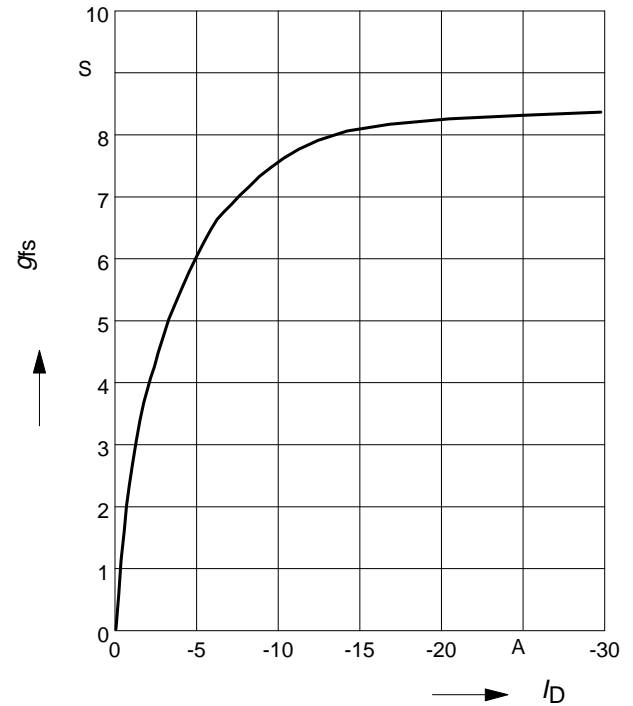
parameter: $t_p = 80 \mu\text{s}$



Typ. forward transconductance

$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$

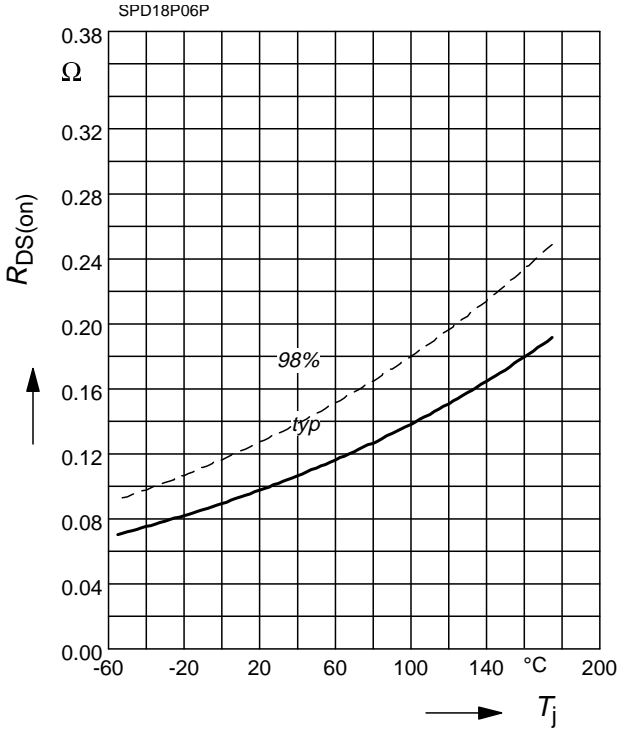
parameter: g_{fs}



Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

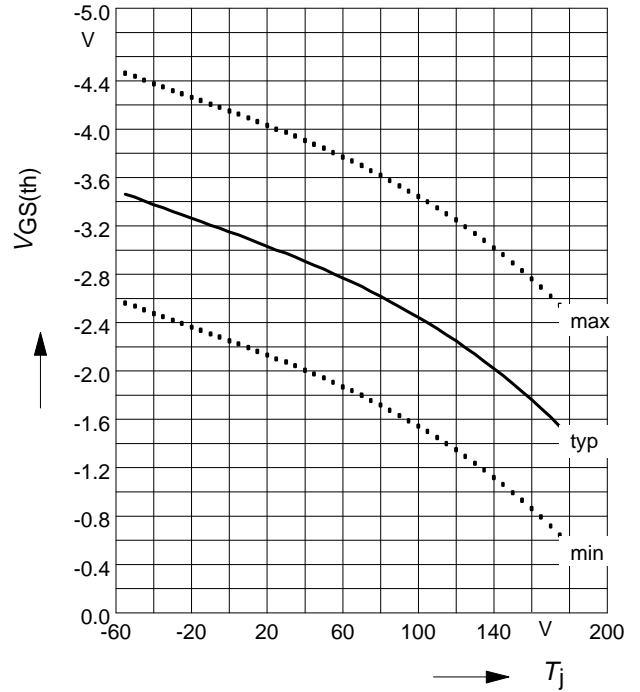
parameter: $I_D = -13.2 \text{ A}$, $V_{GS} = -10 \text{ V}$



Gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

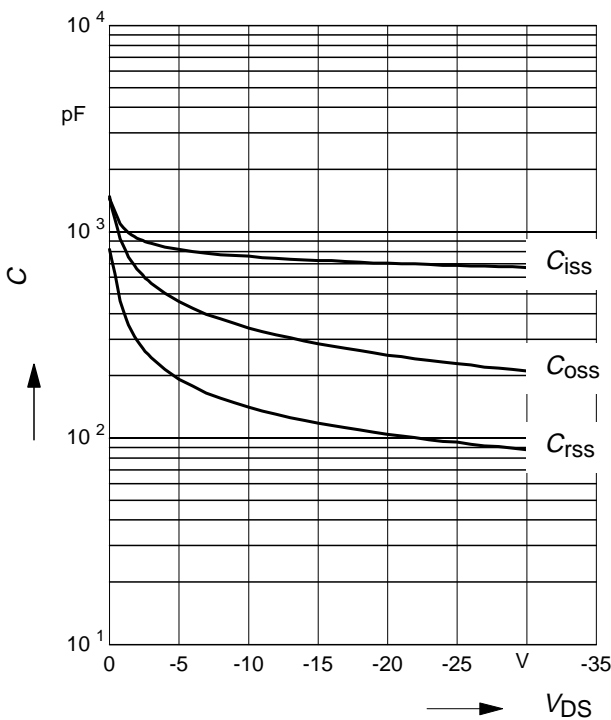
parameter: $V_{GS} = V_{DS}$, $I_D = -1 \text{ mA}$



Typ. capacitances

$$C = f(V_{DS})$$

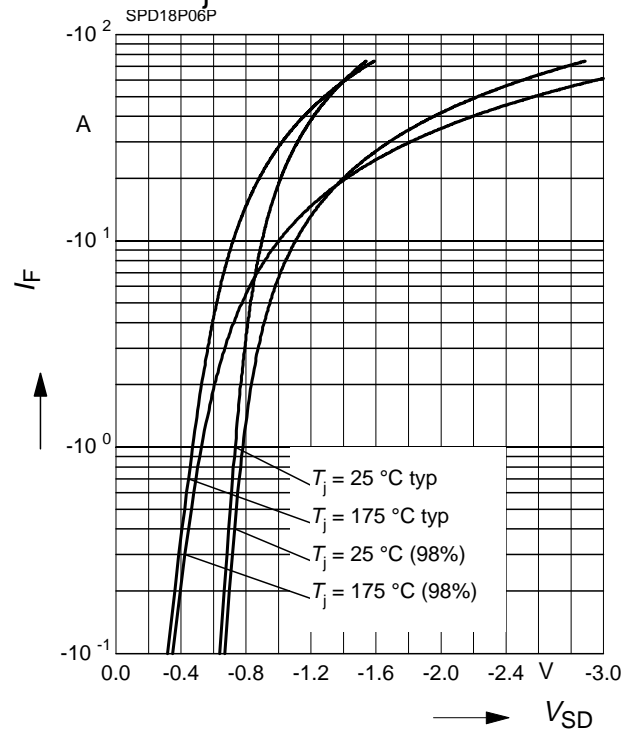
parameter: $V_{GS}=0\text{V}$, $f=1 \text{ MHz}$



Forward characteristics of reverse diode

$$I_F = f(V_{SD})$$

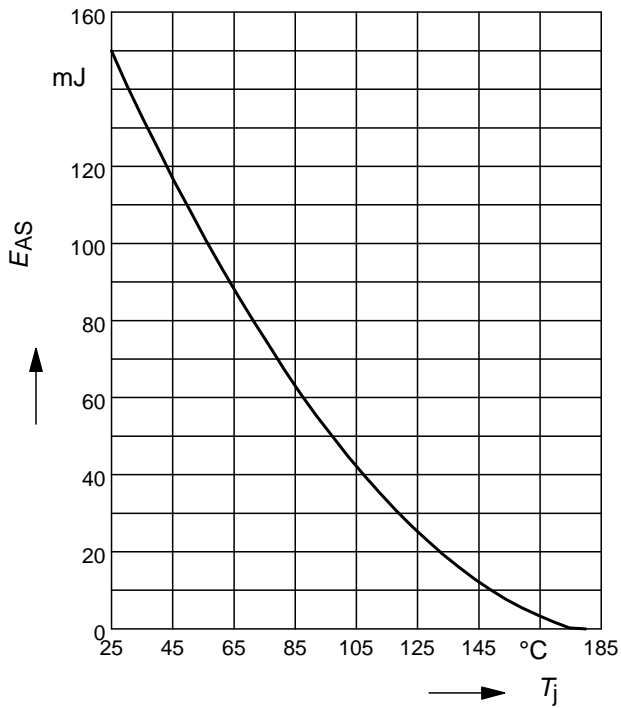
parameter: T_j , $t_p = 80 \mu\text{s}$



Avalanche energy

$$E_{AS} = f(T_j)$$

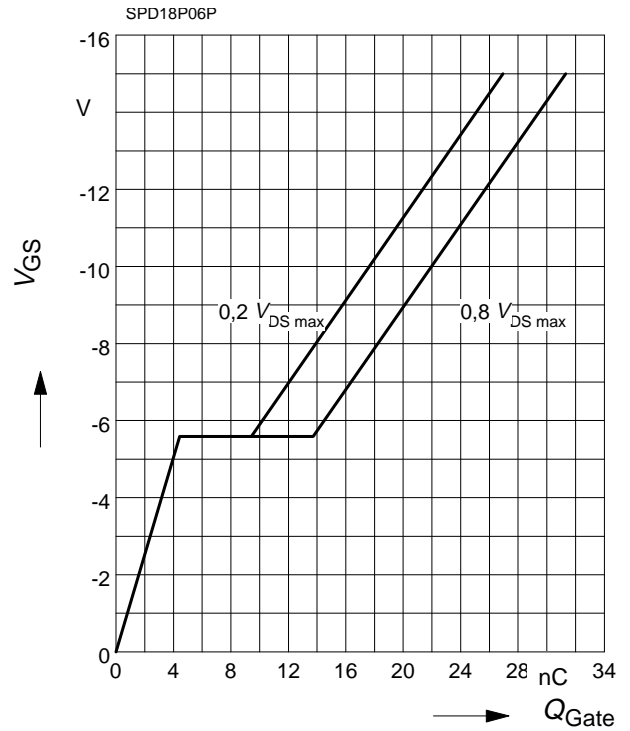
para.: $I_D = -18.6 \text{ A}$, $V_{DD} = -25 \text{ V}$, $R_{GS} = 25$



Typ. gate charge

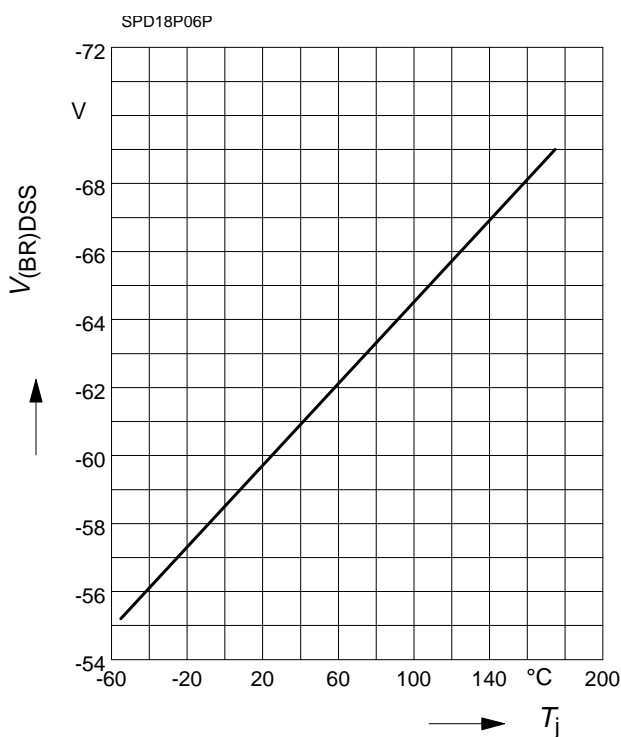
$$V_{GS} = f(Q_{Gate})$$

parameter: $I_D = -18.6 \text{ A}$ pulsed

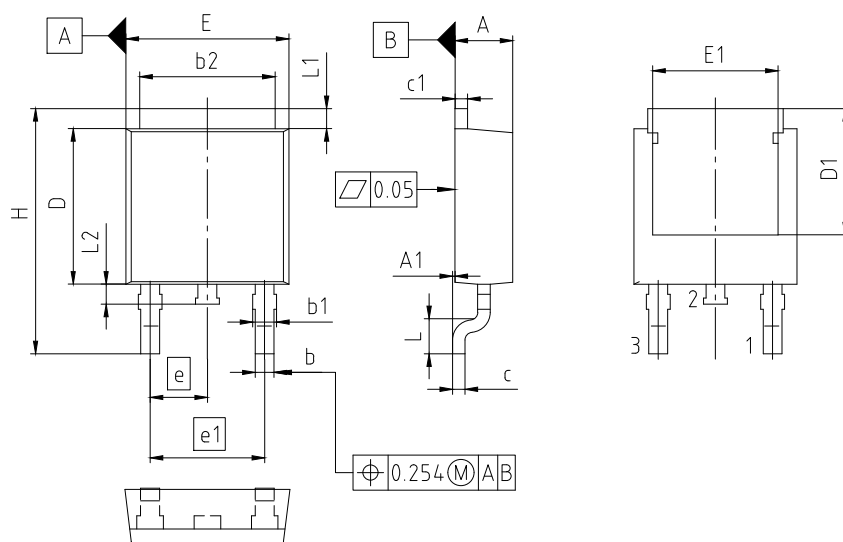


Drain-source breakdown voltage

$$V_{(BR)DSS} = f(T_j)$$



5 Package outlines



PACKAGE - GROUP NUMBER: PG-TO252-3-U02		
DIMENSIONS	MILLIMETERS	
	MIN.	MAX.
A	2.16	2.41
A1	0.00	0.15
b	0.64	0.89
b1	0.65	1.15
b2	4.95	5.50
c	0.46	0.61
c1	0.40	0.98
D	5.97	6.22
D1	5.02	5.84
E	6.35	6.73
E1	4.32	5.50
e	2.29	
e1	4.57	
N	3	
H	9.40	10.48
L	1.18	1.78
L1	0.89	1.27
L2	0.51	1.02

ALL DIMENSIONS REFER TO JEDEC STANDARD TO-252 AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

Figure 1 Outline PG-TO252-3, dimensions in mm

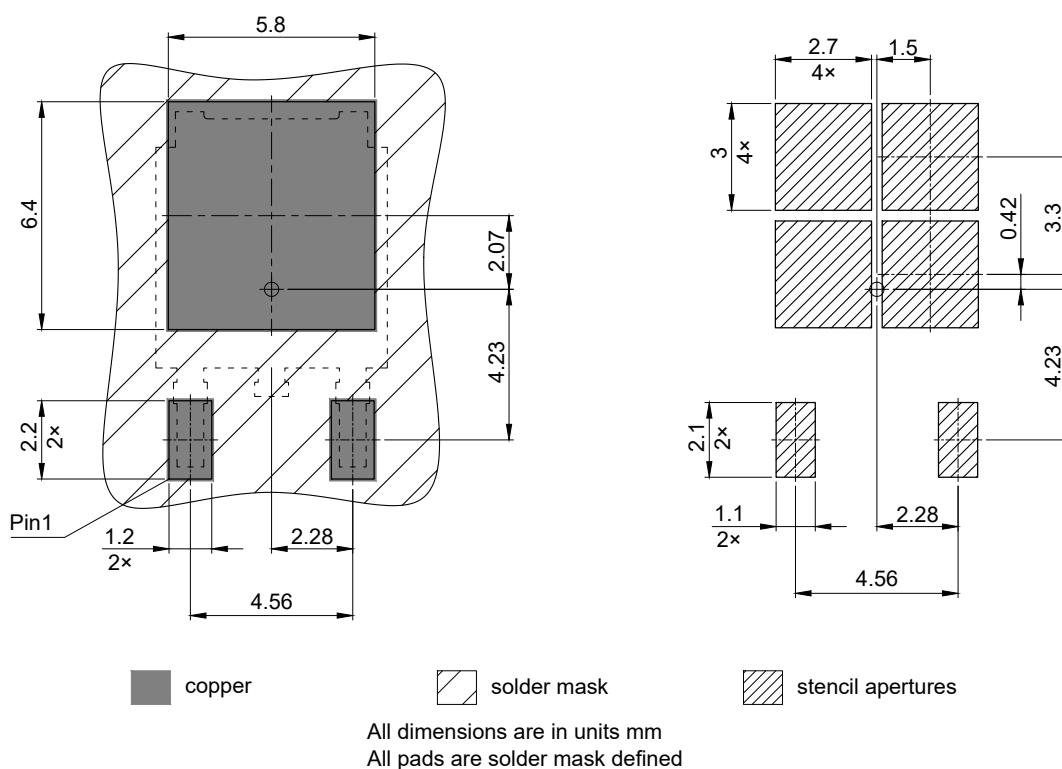
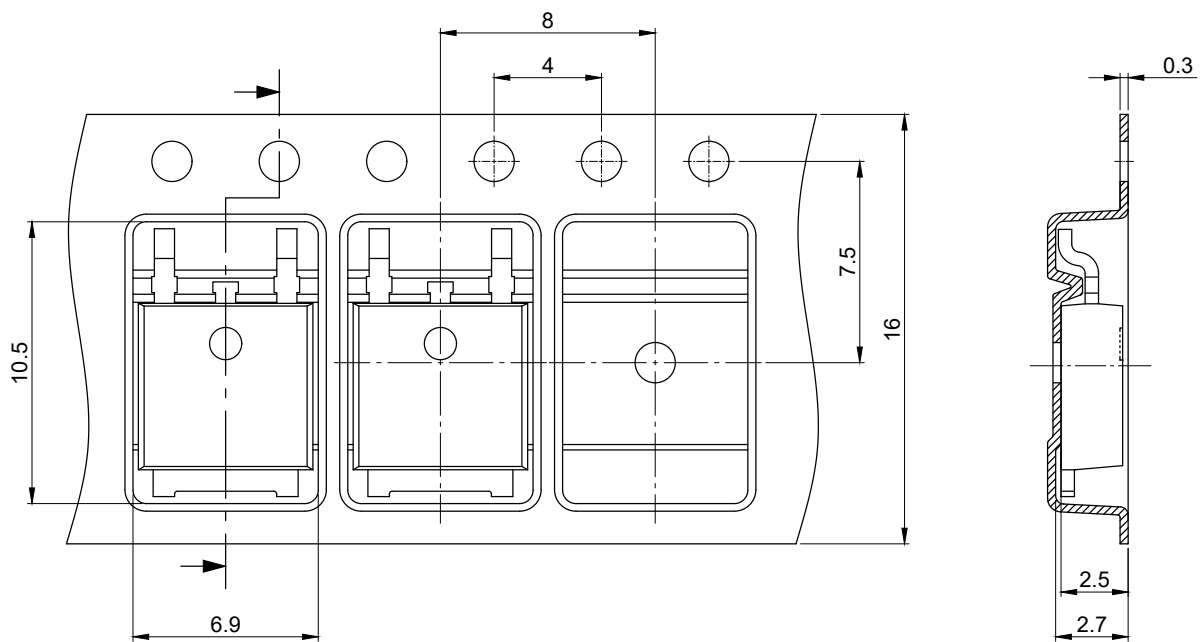


Figure 2 Footprint drawing PG-T0252-3, dimensions in mm




All dimensions are in units mm
The drawing is in compliance with ISO 128-30, Projection Method 1 []

Figure 3 Packaging variant PG-TO252-3, dimensions in mm



Revision history

SPD18P06P G

Revision 2026-03-09, Rev. 1.0

Previous revisions

Revision	Date	Subjects (major changes since last revision)
1.0	2026-03-09	Update to halogen free, features and package drawings

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